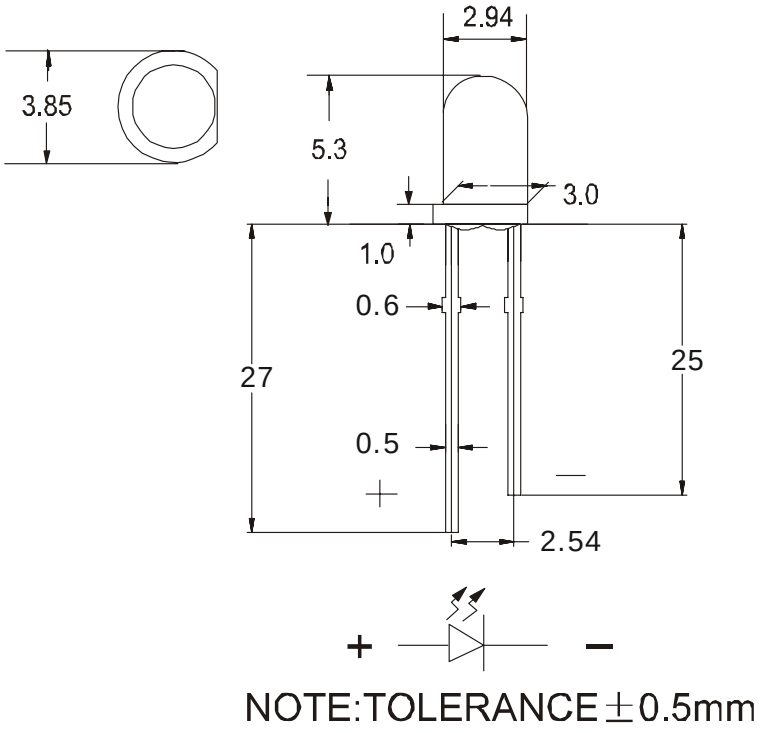
新僑光電
Xin Qiao Optoelectronics

Features

- High radiant intensity
- Peak wavelength= λ_P=940nm
- View angle 50°
- High reliability
- 2.54mm Lead spacing

Package Dimension:



Part NO.	Lens Color
IR304C-AXXXX	Water Clear

Notes:

1. All dimensions are in millimeters.
2. Protruded resin under flange is 1.5mm Max.
3. Lead spacing is measure where the lead emerge from the package.
4. Above specification may be changed without notice.Xinqiao willreserve authority on material change for above specification.
5. There Specifications are subject to change without notice.

Absolute Maximum Ratings at Ta=25℃

Parameter	Symbol	Rating	Unit	Notice
Continuous Forward Current	I_F	40	mA	
Peak Forward Current Pulse width=100 μ s,Duty cycle=1%	I_{FP}	1.0	A	
Reverse Voltage	V_R	5	V	
Operating Temperature	Topr	-40～+85	℃	
Storage Temperature	Tstg	-40～+85	℃	
Soldering Temperature	Tsol	260	℃	4mm from mold body less than 5 seconds
Power Dissipation at(or below) 25℃ Free Air Temperature	Pd	100	mW	

Electrical Optical Characteristics:

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant lntensity	Ee	7		10	MW/sr	I_F=20mA
			40			I_F=100mA,t_P=100 μ s, t_P/T=0.01
			400			I_F=1A, t_P=100 μ s, t_P/T=0.01
Peak Wavelength	λ_P		940		nm	I_F=20mA
Spectral BandWidth	△λ		50		nm	I_F=20mA
Forward Voltage	V_F		1.2	1.4	V	I_F=20mA
			1.35	1.64		I_F=100mA,t_P=100 μ s, t_P/T=0.01
			2.6	4.0		I_F=1A, t_P=100 μ s, t_P/T=0.01
Reverse Current	I_R			10	μ A	V_R=5V
Viewing Angle	$2\theta_{1/2}$		50		Deg	I_F=20mA

Typical Electrical/Optical Characteristics Curves

Fig. 1 Forward Current vs Ambient Temperature

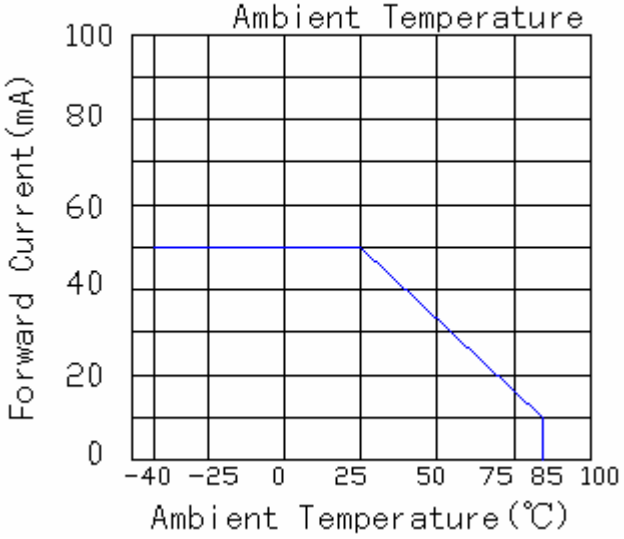


Fig 2. Relative Radiant Power vs. Wavelength

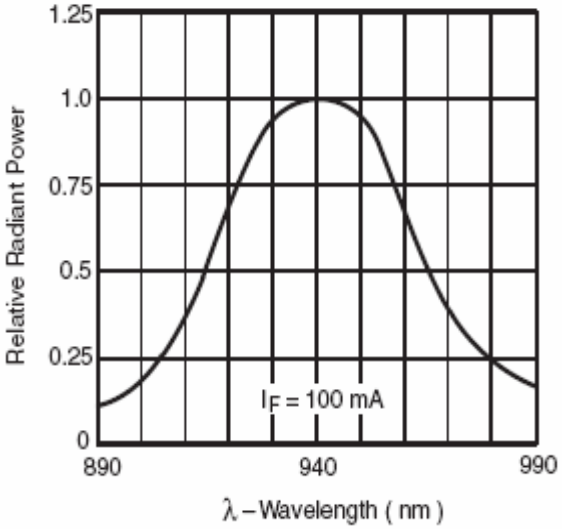


Fig.3 Peak Emission Wavelength vs Ambient Temperature

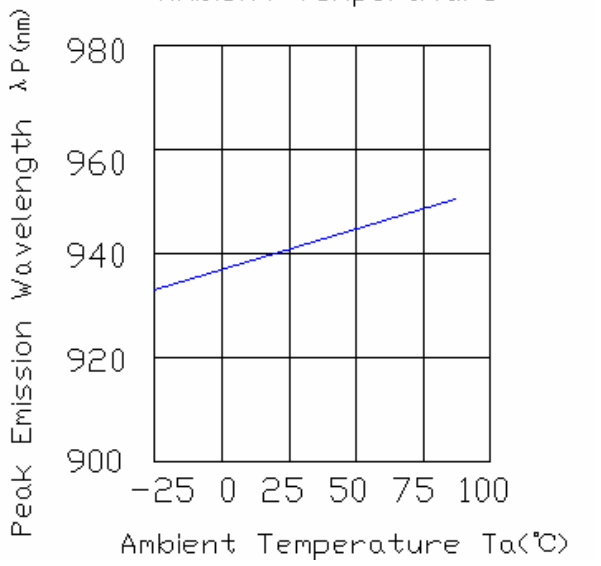
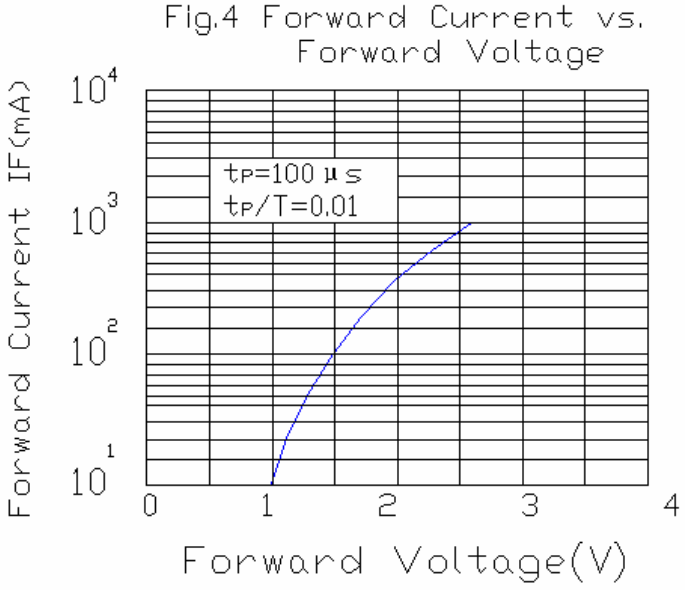


Fig.4 Forward Current vs. Forward Voltage



Typical Electrical/Optical Characteristics Curves

Fig.5 Relative Intensity vs. Forward Current

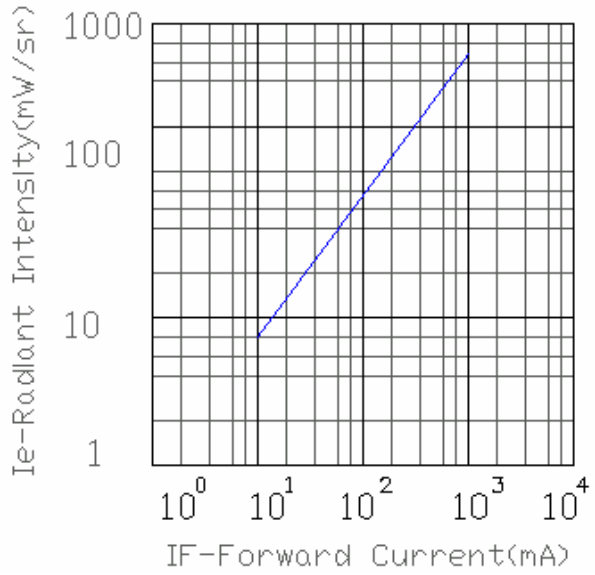


Fig6 Relative Radiant Intensity VS. Angular Displacement

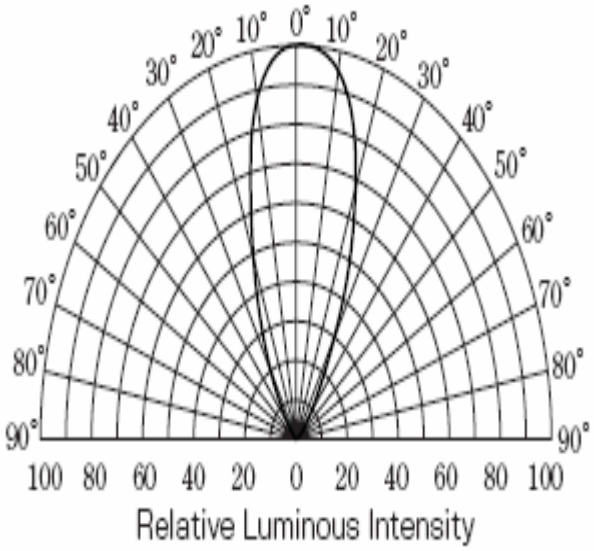


Fig.7 Relative Intensity vs. Amblent Temperature('C)

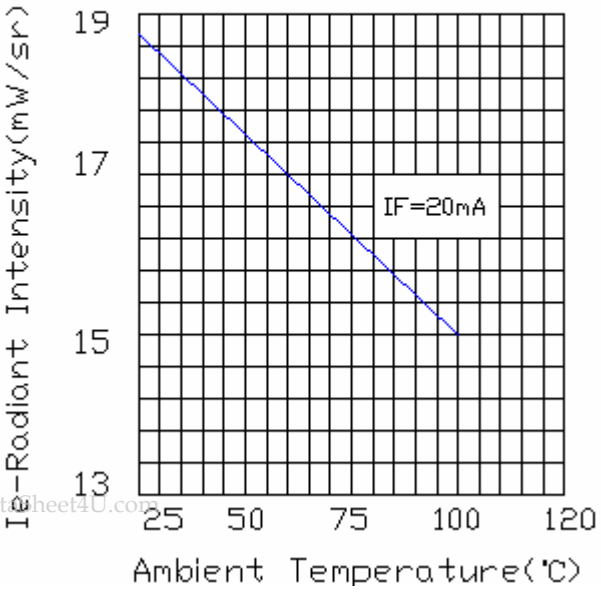


Fig.8 Forward Current vs. Amblent Temperature('C)